# 2 A, 30 V Schottky Barrier Diode

These Schottky barrier diodes are optimized for low forward voltage drop and low leakage current and are offered in a Chip Scale Package (CSP) to reduce board space. The low thermal resistance enables designers to meet the challenging task of achieving higher efficiency and meeting reduced space requirements.

## Features

- Low Forward Voltage Drop 550 mV (Typ.) @  $I_F = 2 A$
- Low Reverse Current  $30 \,\mu\text{A}$  (Typ.) @ V<sub>R</sub> =  $30 \,\text{V}$
- 2 A of Continuous Forward Current
- ESD Rating Human Body Model: Class 3B
  - Machine Model: Class C
- High Switching Speed
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

## **Typical Applications**

- LCD and Keypad Backlighting
- Camera Photo Flash
- Buck and Boost dc-dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

## MAXIMUM RATINGS

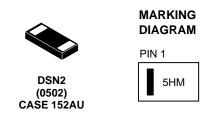
Rating	Symbol	Value	Unit	
Reverse Voltage	V <sub>R</sub>	30	V	
Forward Current (DC)	١ <sub>F</sub>	2	А	
Forward Surge Current (60 Hz @ 1 cycle)	I <sub>FSM</sub>	14	A	
Repetitive Peak Forward Current (Pulse Wave = 1 sec, Duty Cycle = 66%)	I <sub>FRM</sub>	2.9	A	
ESD Rating: Human Body Model Machine Model	ESD	> 8 > 400	kV V	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



# **ON Semiconductor®**

www.onsemi.com



5H = Specific Device Code M = Date Code

## **PIN CONNECTIONS**

1 0 2 CATHODE ANODE

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NSR20305NXT5G	DSN2 (Pb-Free)	5000 / Tape & Reel

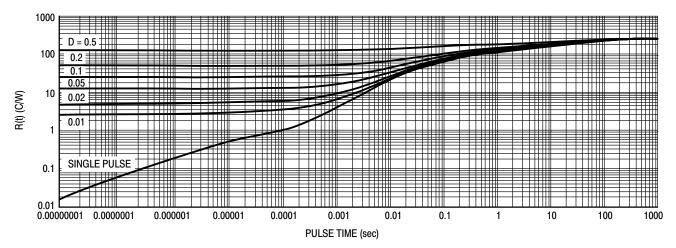
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Min	Тур	Max	Unit
Thermal Resistance Junction–to–Ambient (Note 1) Total Power Dissipation @ $T_A = 25^{\circ}C$	R <sub>θJA</sub> P <sub>D</sub>			255 490	°C/W mW
Thermal Resistance Junction–to–Ambient (Note 2) Total Power Dissipation @ $T_A = 25^{\circ}C$	R <sub>θJA</sub> P <sub>D</sub>			95 1.32	°C/W W
Storage Temperature Range	T <sub>stg</sub>			-40 to +125	°C
Junction Temperature	TJ			+150	°C

1. Mounted onto a 4 in square FR-4 board 50 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.

2. Mounted onto a 4 in square FR-4 board 650 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.





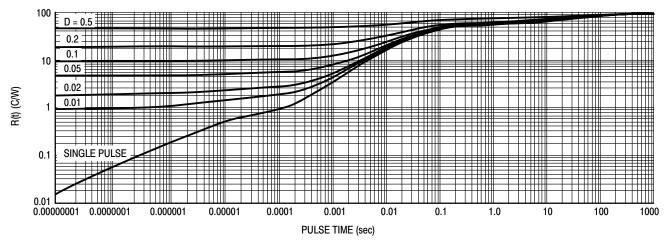
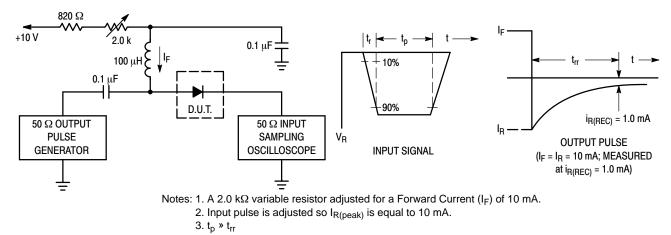


Figure 2. Thermal Response (Note 2)

## **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Мах	Unit
Reverse Leakage $(V_R = 10 V)$ $(V_R = 30 V)$	۱ <sub>R</sub>		3 30	15 100	μΑ
Forward Voltage $(I_F = 10 \text{ mA})$ $(I_F = 100 \text{ mA})$ $(I_F = 500 \text{ mA})$ $(I_F = 1 \text{ A})$ $(I_F = 2 \text{ A})$	VF	- - - - -	255 320 400 455 550	290 360 440 500 600	mV
Total Capacitance ( $V_R = 2.0 \text{ V}, f = 1.0 \text{ MHz}$ )	CT	-	100	-	pF
Reverse Recovery Time (I <sub>F</sub> = I <sub>R</sub> = 10 mA, I <sub>R(REC)</sub> = 1.0 mA, Figure 3)	t <sub>rr</sub>	-	40	-	ns
Peak Forward Recovery Voltage ( $I_F = 100 \text{ mA}, t_r = 20 \text{ ns}, \text{ Figure 4}$ )	V <sub>FRM</sub>	_	470	-	mV

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.





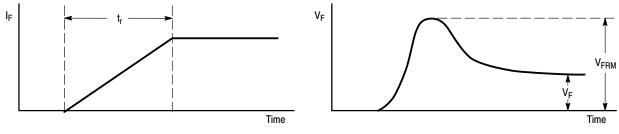
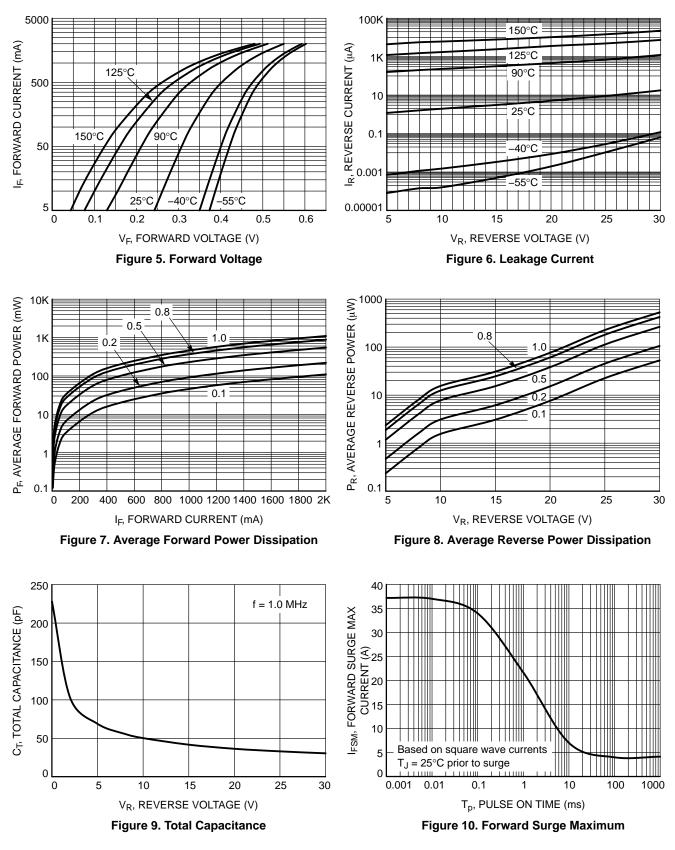


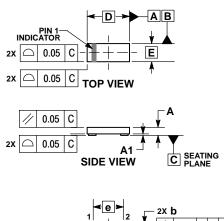
Figure 4. Peak Forward Recover Voltage Definition

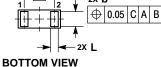
## **TYPICAL CHARACTERISTICS**



### PACKAGE DIMENSIONS

DSN2, 1.4x0.6, 1.00P (0502) CASE 152AU ISSUE A



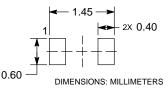


NOTES: 1. DIMENSIONING AND TOLERANCING PER

ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS.



#### RECOMMENDED MOUNTING FOOTPRINT\*



See Application Note AND8464/D for more mounting details

\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdl/Patent-Marking.pdf</u>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights or the rights of others. ON Semiconductor and its officers, employees, subsidiaries, and distributors harmles against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is sub

### PUBLICATION ORDERING INFORMATION

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81–3–5817–1050 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative